8MMINILPD4-CPU

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- Interrupted lines coded with the same letter or letter combinations are electrically connected.
- 2. Device type number is for reference only. The number varies with the manufacturer.
- 3. Special signal usage:
 - _B Denotes Active-Low Signal
 - or [] Denotes Vectored Signals
- 4. Interpret diagram in accordance with American National Standards Institute specifications, current revision, with the exception of logic block symbology.

Preliminary - Subject to Change without Notice!

This board was designed for maximum flexibility in software development and demonstrates multiple functions possible with i.MX processors. Although best design practices have been applied, some areas may not be suitable for a mass-production design.

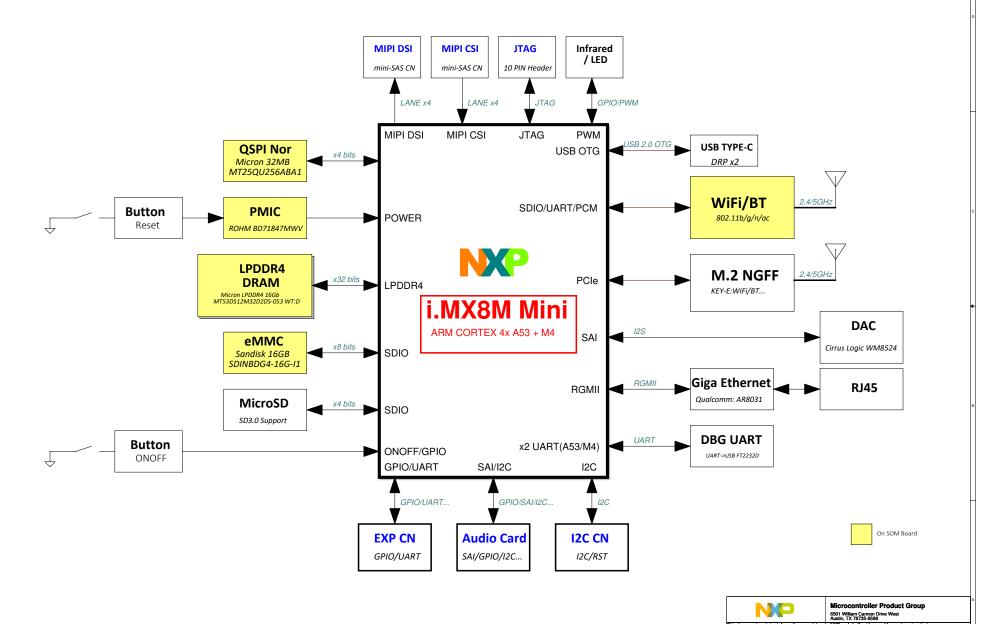
(i.MX8M Mini Reference Board)

Revision History

Rev. Code	Date	Ву	Description
А	2018-03-12	Frank	Initial version
A1	2018-03-27	Frank	1. Update U1 I.MX8M Mini symbol naming.
В	2018-05-01	Frank	Change PMIC U8 to BD71847; Add external PU resistor R133 for SD2_nRST, as internal is PD and ROM won't pull it to high; DNP R63,R64,C389,C390, as internal VREF works well;
B1	2018-06-19	Frank	Remove the IOMUX table;
С	2018-09-12	Frank	1. Remove optional 32K Crystal Circuit for i.MX8M Mini; 2. Remove external DDR VREF Circuit as Internal works well; 3. Add R134, R135 for BOOT_MODE3 option to TESTMODE for compatible design with i.MX8M Nano; 4. Change J4_Pin56 from GND to TESTMODE(BOOT_MODE3) for compatible design with i.MX8M Nano; 5. Remove R50, R62, R107, R128 to simplify the optional design; 6. Remove C7 for NVCC_3V3; 7. Update the symbol of i.MX8M Mini: > Correct power domain for B27, 25 from NVCC_C1P8; > Correct power domain for B27, 25 from NVCC_C1K fix VDD_24M_XTAL_1P8; > Correct power domain for B27, 25 from NVCC_C1K fix VDD_24M_XTAL_1P8; > Correct power domain for B27, 25 from NVCC_C1K fix VDD_24M_XTAL_1P8; > Correct power domain for D22, E1P D23, E22 by VDD_18B_1P8, and also adjust the pin locations. 8. Update the description of the Block Diagram and Power Tree; 9. Update some descriptions of the schematic; 10. Add R136, C405 on VDD_MIP1_1V2 for compatible design with i.MX8M Nano;
C1	2018-11-29	Frank	1. Remove the note for R136;
C2	2019-1-31	Frank	1. Update the Min/Typ/Max operating range for I.MX8M Mini power supplies; 2. Add note for changing BD71847 BUCK1/2/5 output voltage according to the new operation range; 3. Add note for all IOs that internal pull up/down is not supported in 3.3V mode;

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8MMINILPD4-EVK Block Diagram

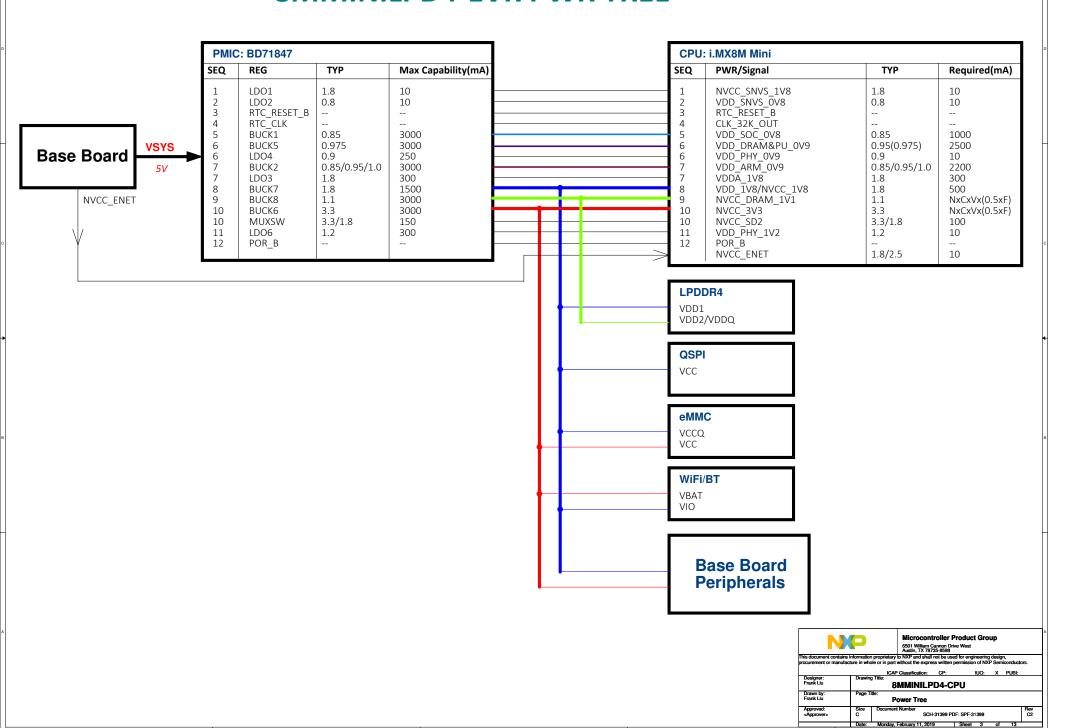


8MMINILPD4-CPU Block Diagram

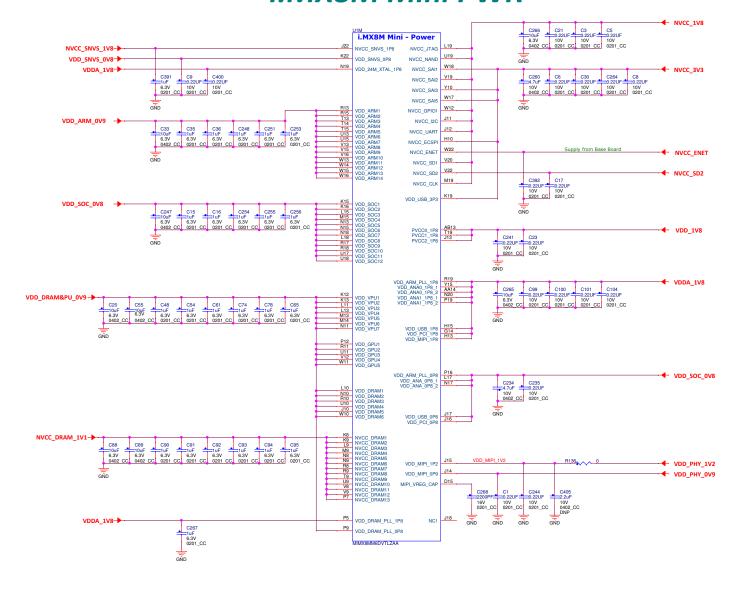
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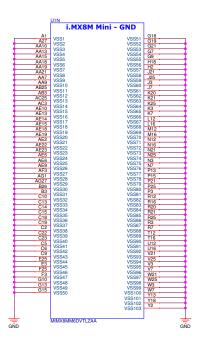
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8MMINILPD4-EVK PWR TREE



i.MX8M Mini PWR





VDD_3V3

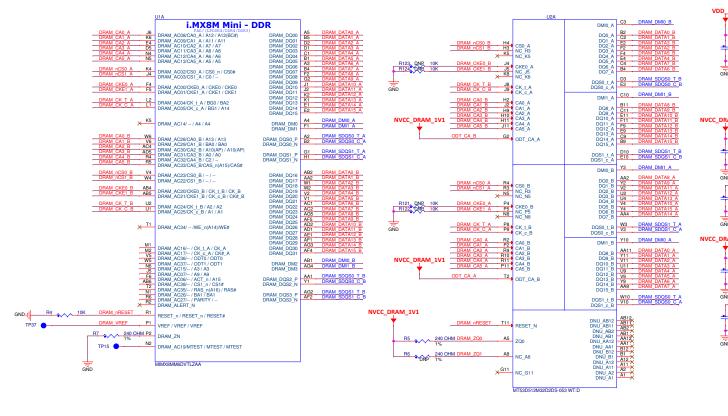
VDD_1V8

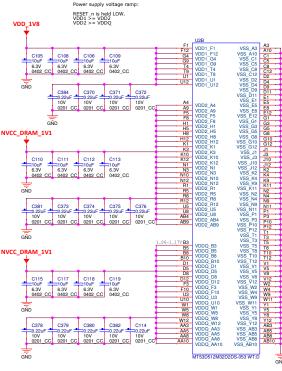


NVCC 3V3

NVCC_1V8

LPDDR4 2GB





Data Bus Command/Address
me LPDDR4 DDR4 Pin Name LPDDR4 DD

Pin Name	LPDDR4	DDR4	Pin Name	LPDDR4	DDR4
Pin Name DRAM 2050 P. DRAM 2051 P. DRAM 2052 P. DRAM 2051 P. DRAM 2053 P. DRAM 2054 P. DRAM 2054 P. DRAM 2054 P. DRAM 2054 P. DRAM 2	LPDDR4 LPDDR4 DS9 (-A	DDR4 DOR1_CA DOS1_CA DOS1_C	Pin Name DBAM RESET N DBAM ALEPT N DBAM ALEPT N DBAM ACO N DB	LPDDRA RESET N MISST I GOST A	DDR4 RESET_n / MTEST1 COLOR ALERT_n / MTEST1 COLOR COLOR COLOR ALERT_N / MTEST1 COLOR ALERT_N / MTEST1 COLOR ALERT_N / MTEST1 ALERT_N / MTEST1
DRAM_DQ31	DQ15_B	DQU7_B			

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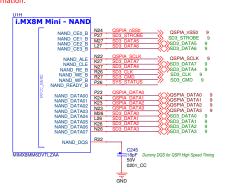
i.MX8M Mini IO Interface

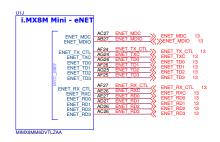
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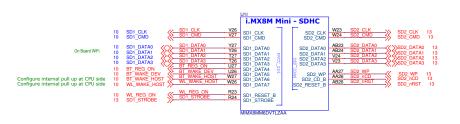
IO internal pull up/down is not supported in 3.3V mode, must disable the internal pull up/down via software and use external pull up/down resistors instead.

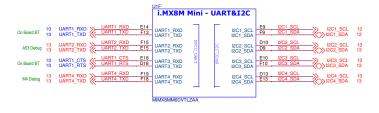
All IO pin groups are impacted except for XTAL, DDR, PCI, USB and MIPI PHY IO's.

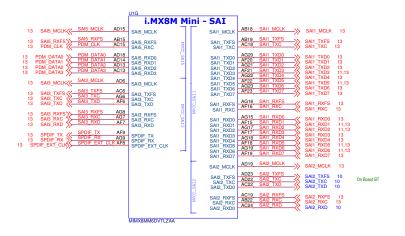
See Errata e50080 for detailed information.



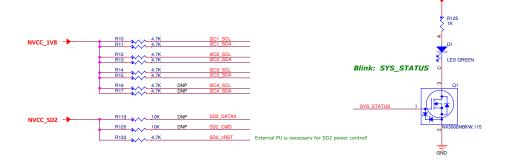








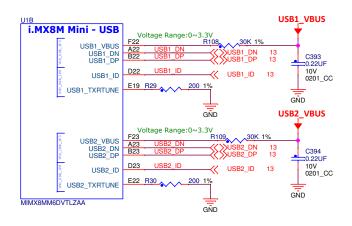


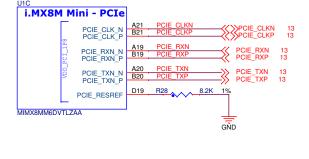


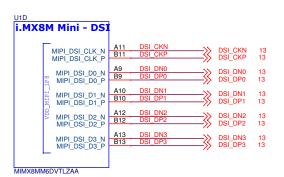
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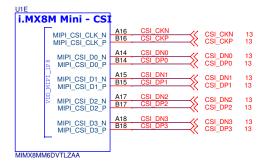
LED VDD_3V3

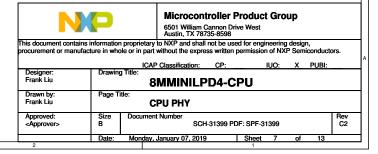
i.MX8M Mini PHYs

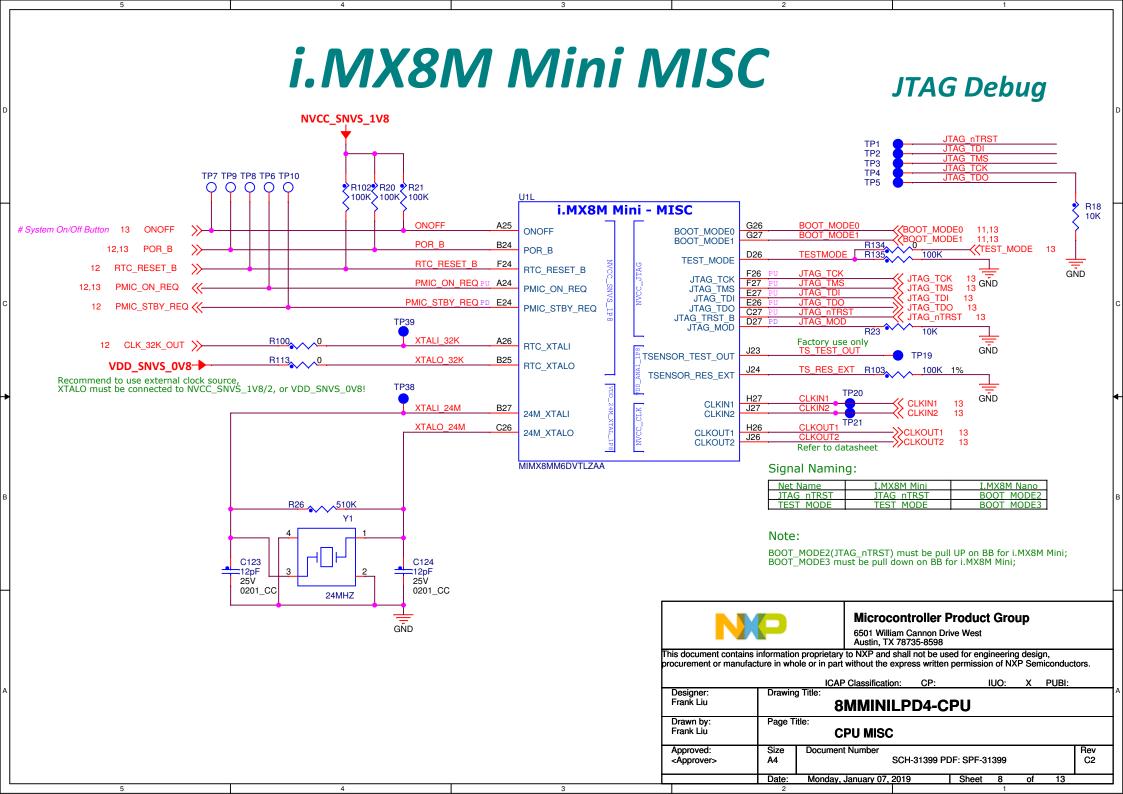


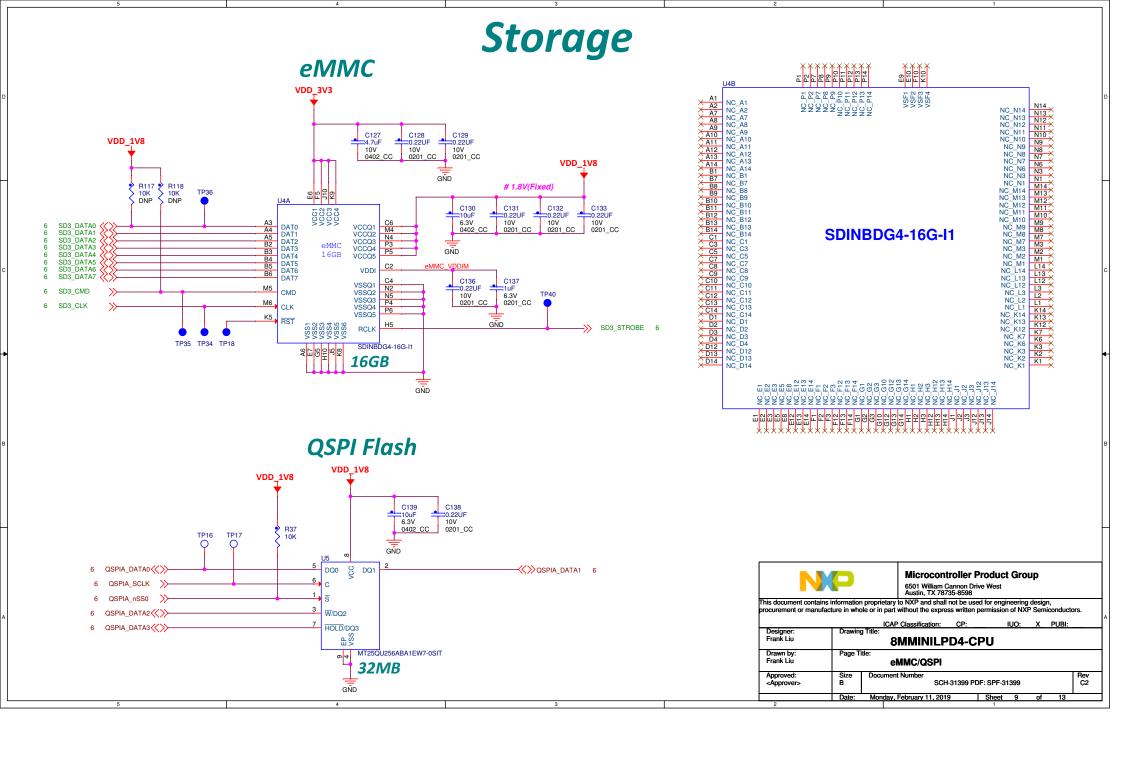


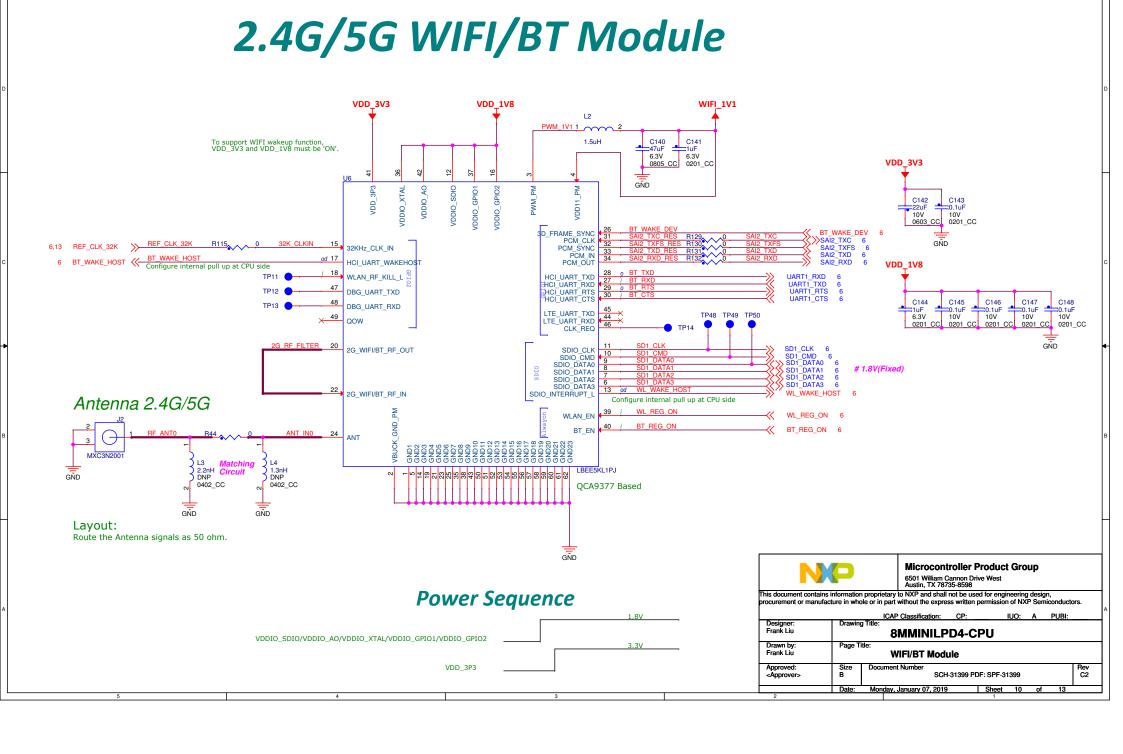












Boot Mode and CFG Switch

Caution

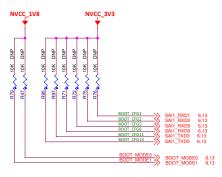
IO internal pull up/down is not supported in 3.3V mode, must disable the internal pull up/down via software and use external pull up/down resistors instead. All IO pin groups are impacted except for XTAL, DDR, PCI, USB and MIPI PHY IO's. See Errata e50080 for detailed information.

i.MX8M Mini ROM Fuse

	Address	7	6	5	4	3	2	1	0
	0x470[15:8]	BOOT_CFG[15]	BOOT_CFG[14]	BOOT_CFG[13]	BOOT_CFG[12]	BOOT_CFG[11]	BOOT_CFG[10]	BOOT_CFG[9]	BOOT_CFG[8]
	0x470[15:8] 0x470[15:8]	-		001 - SD/eSD 010 - MMC/eMMC			Port Select: 00 - uSDHC1		
	0x470[15:8]	Infinit-Loop (Debug USE only)		011 - NAND		00 - 1: 01 - 6: 10 - 3:	Pages In Block: Nand_F 00 - 128 00 - 3 01 - 64 01 - 2 10 - 32 10 - 4 11 - 256 11 - 5		
	0x470[15:8]	0 - Disable 1 - Enable		100 - QSPI		Flash Auto Probe	FLASH_TYPE 000-Device supports 3B read b 001-Device supports 4B read b 010-HyperFlash 1V8 011-HyperFlash 3V3 100-MMIC Octal DDR		y default y default
	0x470[15:8]			110 - SPI NOR			Port Select: 000 - eCSPI1 001 - eCSPI2 010 - eCSPI3		SPI Addressing: 0 - 3-bytes (24-bit) 1 - 2-bytes (16-bit)
	0x470[15:8]		Others - Res	erved for future use					
		BOOT_CFG[7]	BOOT_CFG[6]	BOOT_CFG[5]	BOOT_CFG[4]	BOOT_CFG[3]	BOOT_CFG[2]	BOOT_CFG[1]	BOOT_CFG[0]
SD/eSD	0x470[7:0]	Fast Boot: 0 - Regular	Reserved	Reserved	Bus Width: 0 - 1-bit 1 - 4-bit	Speed 000 - Normal/SDR12 001 - High/SDR25 010 - SDR50 011 - SDR104 101 - Reserved for DDR50 Others - Reserved 011 - Reserved 012 - Reserved 013 - Reserved 014 - Reserved 015 - Reserved			Reserved
MMC/eMMC	0x470[7:0]	1 - Fast Boot	Bus Width: 000 - 1-bit 001 - 4-bit 010 - 8-bit 101 - 4-bit DDR (MMC 4.4) 110 - 8-bit DDR (MMC 4.4) Else - reserved.			Speed USDHC 10 VOLTAGE On Normal USDHC 10 VOLTAGE SELECTION For 10 - Reserved for HS200 11 - Reserved Normal Boot Mode 0 - 3.3V 1 - 1.8V			USDHC IO VOLTAGE SELECTION For Manufacture Mode 0 - 3.3V 1 - 1.8V
NAND	0x470[7:0]	BT_TOGGLEMODE	BOOT_SEA 00 - 2 01 - 2 10 - 4 11 - 8	BOOT_SEARCH_COUNT: 00 00 - 2 00 1 - 2 10 - 4 11 - 8 11			Toggle Mode 33MHz Preamble Delay, Read Latency: '000' - 16 GPMICLK cycles. '001' - 15 GPMICLK cycles. '010' - 2 GPMICLK cycles. '100' - 4 GPMICLK cycles. '100' - 4 GPMICLK cycles. '100' - 4 GPMICLK cycles. '110' - 5 GPMICLK cycles. '111' - 15 GPMICLK cycles. '111' - 15 GPMICLK cycles. '111' - 15 GPMICLK cycles.		
FlexSPI	0x470[7:0]	HOLD 00 - 5 01 - 1 10 - 3 11 - 1	00us ms ms	FLASH Auto Probe Type			FlexSPI FLASH	Dummy Cycle	
SPINOR	0x470[7:0]	CS select SPI only: 00 - CS#0 default 01 - CS#1 10 - CS#2 11 - CS#3	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved

BT CFG Pins:

BOOT_CFG0 SAI1 RXD1 BOOT CFG1 SAI1_RXD2 BOOT_CFG2 SAI1_RXD3 BOOT_CFG3 SAI1_RXD4 BOOT_CFG4 SAI1_RXD5 BOOT_CFG5 SAI1_RXD6 BOOT_CFG6 SAI1_RXD7 BOOT_CFG7 SAI1_RXD8 BOOT_CFG8 SAI1 RXD9 BOOT CFG9 SAI1_RXD10 BOOT_CFG10 SAI1 RXD11 BOOT CFG11 SAI1 RXD12 BOOT CFG12 SAI1_RXD13 BOOT_CFG13 SAI1 RXD14 BOOT CFG14 SAI1_RXD15 BOOT_CFG15



Note:

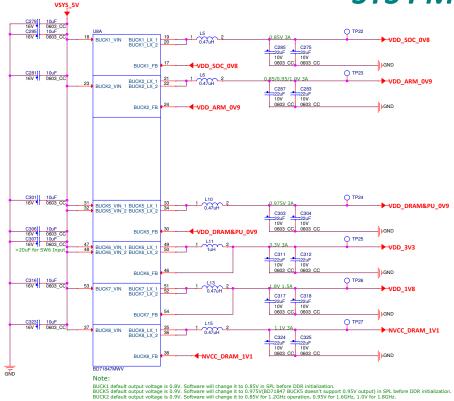
- Bootcfg/SAI1 singals have internal PD before and after POR_B reset is deasserted!
- 2. Standalone SOM board can support eMMC/SDHC3 boot, by populating R71, R72, R75, R76, R79, R95, R97!
- 3. When using Base Board for Multi boot selection, you must keep the resistors DNP on SOM board!

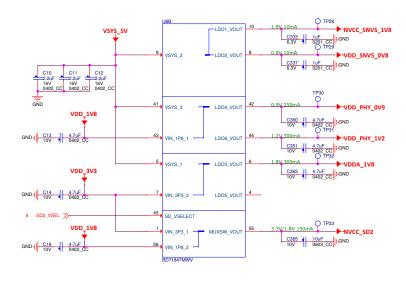
Boot Mode

BO	OT_MODE1	BOOT_MODE0
во	ОТ ТҮРЕ:	
00	Boot From F	uses
01	Serial Down	loader
10	Internal Bo	ot (Development)
11	Reserved	

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			express written po	ermission of NX		ors.
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SYS PMIC





GND Testpoints



Backup PWR Supply



		NVCC_SNVS_1V8	TP52		
TP53	GND	1uF 0201_CC	INTLDO_1V	75 C273 1uF 1uGNI	D
6 12C1_SCL >>	R48 0 26	SCL SDA	C32K_OUT	29	—≫CLK_32K_OUT 8
# CPU WDOG_B Reset 6 WDOG_B	R106 DNP 100K R55 0 2	WDOG PMIC_ON_REQ	IRQ	39 00	→>>PMIC_nINT 6
8 PMIC_STBY_REQ >>	R52 0 16	PMIC_STBY_REQ	POR RTC_RESET	25 OD R114 0 3 OD R111 0	→>>POR_B 8,13 →>>RTC_RESET_B 8
1M DNP 2 2 1 C298 1 1697 2 2 1 C298 1 2 7 584 Hz	XIN 32K 14 XOUT 32K 13 C209 IBpF 50V 0201 CC	XIN SOUT SOUTH SOU	58 69 PGND2 60 PGND4 61 PGND4 61 PGND5		

1. PWRON is used as RESET Button as default, need to configure PWRON long push as 10ms, Cold Reset, and short push detect should be disabled!

2. WDOG B is used as Cold Reset, external pull up is needed. On EVK, R106 is not necessary, since WDOG B/GPI01.1002 of CPU has internal pull up.

	i.MX8	M Mini LPDDR4 EVK Po	wer Sequence				
	SEQ	PWR/Signal	REG	MIN	ТҮР	MAX	Max Current(mA)
;	1 2 3 4 5 6 6 7 7 8 9 10 10 11 12	NVCC_SNVS_1V8 VDD_SNVS_0V8 RTC_RESET_B CLK_32K_OUT VDD_SOC_0V8 VDD_DRAM&PU_0V9 VDD_PHY_0V9 VDD_ARM_0V9 VDDA_1V8 VDD_1V8/NVCC_1V8 NVCC_DRAM_1V1 VDD_3V3/NVCC_3V3 NVCC_SD2 VDD_PHY_1V2 POR_B	LDO1 LDO2 RTC_RESET_B RTC_CLK BUCK1 BUCK5 LDO4 BUCK2 LDO3 BUCK7 BUCK8 BUCK6 MUXSW LDO6 POR_B	1.62 0.76 0.78/0.805 0.805/0.855 0.805/0.9/0.95 1.71 1.65 1.06 3 3.0/1.65 1.14	1.8 0.8 0.82/0.85 0.85/0.95 0.9 0.85/0.95/1.0 1.8 1.8 1.1 3.3 3.3/1.8 1.2	1.98 0.9 0.9 0.9/1.0 1.0 0.95/1.0/1.05 1.89 1.95 1.14 3.6 3.6/1.95 1.26	10 10 3000 3000 250 3000 300 1500 3000 3000 150 3000

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Frank Liu	PMIC						
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	Date: Monday, February 11, 2019 Sheet 12 of 13						

B2B Connector for CPU Board Caution: IO internal pull up/down is not supported in 3.3V mode, must disable the internal pull up/down via software and use external pull up/down resistors instead. All IO pin groups are impacted except for XTAL, DDR, PCI, USB and MIPI PHY IO's. See Errata e50080 for detailed information. Receptacle Header VSYS_5V -VSYS_5V VSYS_5V UART3 RXD HARTS CTS 10uF 16V 0603_CC 0603_CC 19 21 23 25 27 29 31 VDD_3V3 ◆ VDD 1V8 GND I2C3 SCL DSI DP3 VDD 3V3 **VDD 1V8** 32 I2C4_SDA (C) A53 Debug UART2_TXD 39 41 43 SYS_nRST SAI3_MCLK SAI3_TXFS GPIO1_IO14 GPIO1_IO13 C403 22uF M4 Debug C404 UART4_TXD GPI01 I012 10V 10V 0603 CC 0603 CC 47 49 51 53 55 57 59 61 63 65 67 69 8,12 POR_E SAI3_TXD SAI3_RXFS GPIO1_IO10 GPIO1_IO09 GPIO1_IO08 GND JTAG_TDO JTAG_TDI CSL DN2 GND CSI DP2 SAI3 RXC CSI_DN3 GPIO1_I006 60 62 64 66 JTAG_nTRST JTAG_TCK CSI_DP3 SPDIF RX GPIO1_I001 CLKOUT1 65 PCIE_RXP PDM_CLK PDM DATAN SAI2 BXFS PDM DATA1 SAI5 RXFS SD2_DATA2 73 75 77 79 81 83 85 87 89 SD2_DATA3 PDM DATA3 SAI1_RXFS SAIT BXC PCIE_CLKP SAI5 MCLK SAI1 RXD0 SAI2 RXC SAI1 RXD1 USB1_VBUS SD2_DATA0 SD2_WP 86 SAII_TXD1 SAI1 RXD3 88 90 92 SD2 nCD SAI1 RXD4 USB1 ID SAI1_RXD5 SAI1_TXD3 SAI1_TXD4 SAI1_TXD5 6,11 USB2 VBUS SAIT BYD6 93 95 97 SAI1 BXD CLKIN1 SAI1 BXD7 6,11 CLKIN2 100 100 USB2_ID 7 SAI1_TXFS BOOT MODE1 DF40C-100DP-0.4V(51) DF40C-100DS-0.4V(51) GND Receptacle 00 | 2 ENET_RX_CTL 6 ENET_TXC When using M.2 WIFI Module, remove R115, populate R116! **Microcontroller Product Group** 6 ENET TXC ENET RD0 6501 William Cannon Drive West Austin, TX 78735-8598 ENET_TD1 ENET_RD2 This document contains information proprietary to NXP and shall not be used for engineering design, procurement or manufacture in whole or in part without the express written permission of NXP Semiconductors. S ENET_RD3 ENET_MDC ICAP Classification: NVCC_ENET Designer: Frank Liu C2 DF40C-20DS-0.4V(51) 8MMINILPD4-CPU 2.2uF GND GND 10V Page Title: 0402_CC Frank Liu **SOM Interface** Approved: Rev C2 GND GND GND <Approver> SCH-31399 PDF: SPF-31399 Friday, January 25, 2019 Sheet 13